

Product Specifications

Part Number ⁶	OCL ¹ (μ H) $\pm 20\%$	FLL ² (μ H) minimum	I_{rms}^3 (A)	I_{sat}^4 (A)	DCR (m Ω) typical @ +20 °C	DCR (m Ω) maximum @ +20 °C	K-factor ⁵
HCM0703-R15-R	0.15	0.09	26	52	1.9	2.5	1044
HCM0703-R22-R	0.22	0.13	23	40	2.5	2.8	986
HCM0703-R47-R	0.47	0.28	17.5	26	4.0	4.2	580
HCM0703-R68-R	0.68	0.41	15.5	25	5.0	5.5	455
HCM0703-R82-R	0.82	0.49	13	24	6.7	8.0	439
HCM0703- 1R0-R	1.0	0.60	11	22	9.0	10	374
HCM0703- 1R5-R	1.5	0.90	9.0	18	14	15	366
HCM0703- 2R2-R	2.2	1.3	8.0	14	18	20	281
HCM0703- 3R3-R	3.3	2.0	6.0	13.5	28	30	252
HCM0703- 4R7-R	4.7	2.8	5.5	10	37	40	210
HCM0703- 6R8-R	6.8	4.1	4.5	8.0	54	60	151
HCM0703- 8R2-R	8.2	4.9	4.0	7.5	64	68	142
HCM0703- 100-R	10	6.0	3.2	7.0	71	78	132
HCM0703- 150-R	14.9 \pm 15%	10.1	2.2	5.0	113	127	105
HCM0703- 220-R	22	14.1	2.3	3.0	135	149	83
HCM0703- 330-R	33	19.8	1.8	2.2	220	242	76

1. Open Circuit Inductance (OCL) Test Parameters: 100 kHz, 0.25 V_{max}, 0.0 Adc, +25 °C.

2. Full Load Inductance (FLL) Test Parameters: 100 kHz, 0.25 V_{max}, I_{sat} @ +25 °C.

3. I_{DC}: DC current for an approximate temperature rise of 40 °C without core loss. Derating is necessary for AC currents.

PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed +125 °C under worst case operating conditions verified in the end application.

4. I_{sat}: Peak current for approximately 20% rolloff at +25 °C.

5. K-factor: Used to determine B_{pp} for core loss (see graph). B_{p-p} = K * L * Δ I. B_{pp}: (Gauss), K: (K-factor from table), L: (Inductance in μ H), Δ I (Peak to peak ripple current in Amps).

6. Part Number Definition: HCM0703-xxx-R

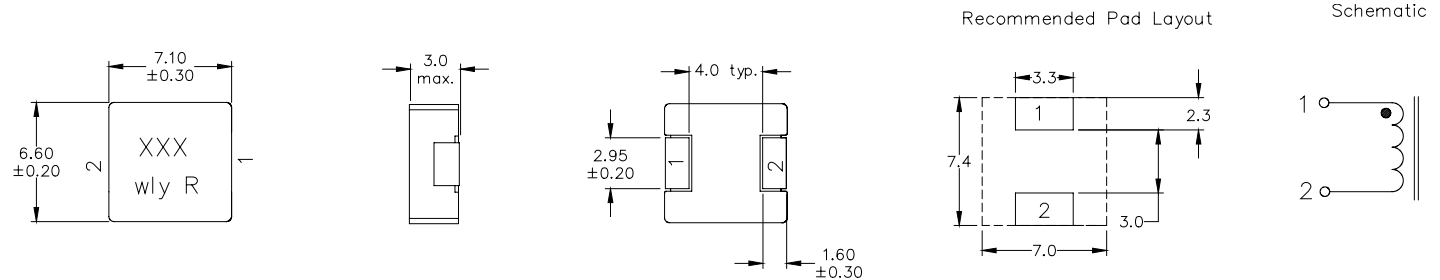
HCM0703 = Product code and size

-xxx= Inductance value in μ H, R = decimal point,

if no R is present then last character equals number of zeros.

"-R" suffix = RoHS compliant

Dimensions (mm)



Part marking: XXX=Inductance value in uH, R= decimal point. If no R is present then last character equals number of zeros.

wly=date code, R=revision level

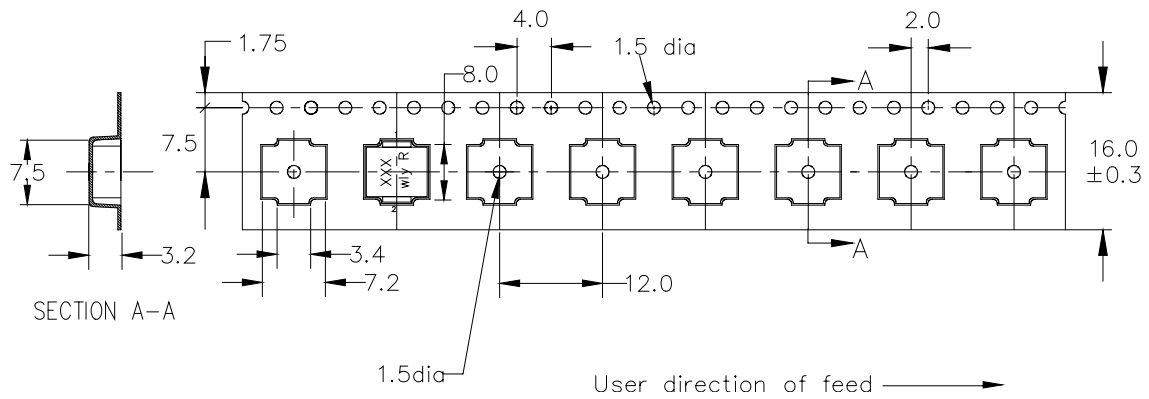
All soldering surfaces to be coplanar within 0.10 millimeters

Tolerances are \pm 0.3 millimeters unless stated otherwise

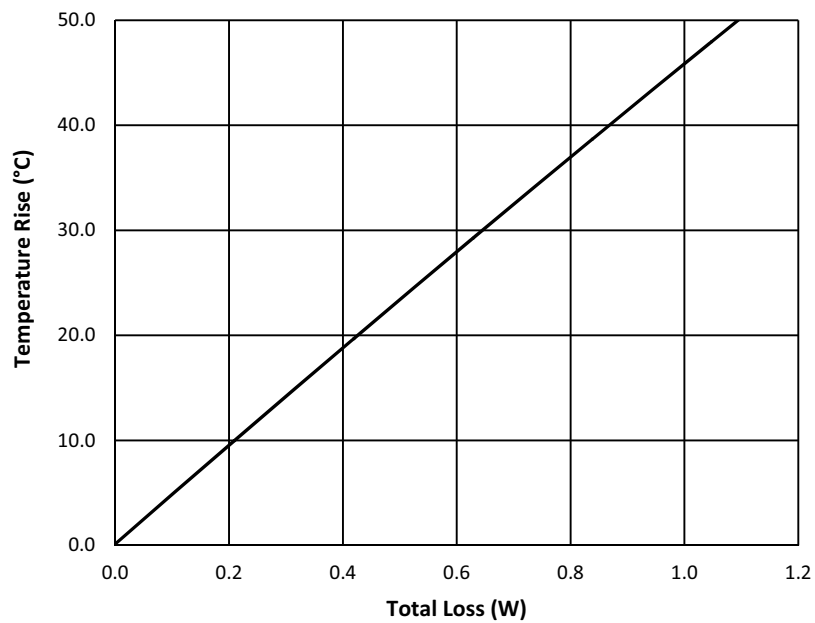
Color: Grey

Packaging information (mm)

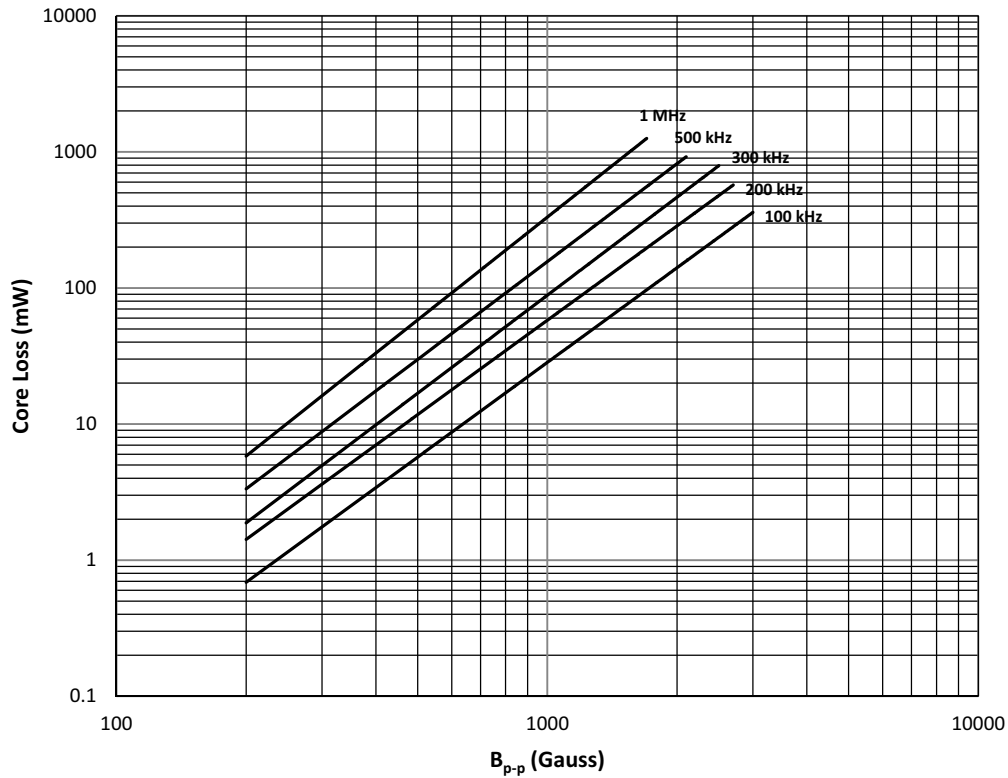
Supplied in tape and reel packaging, 1500 parts per 13" diameter reel.



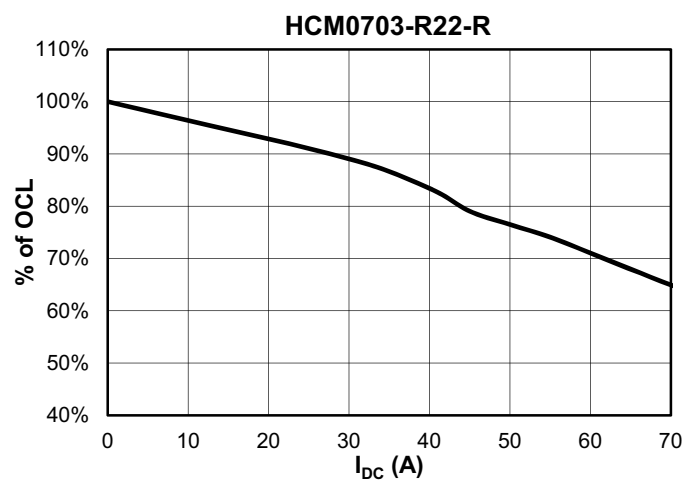
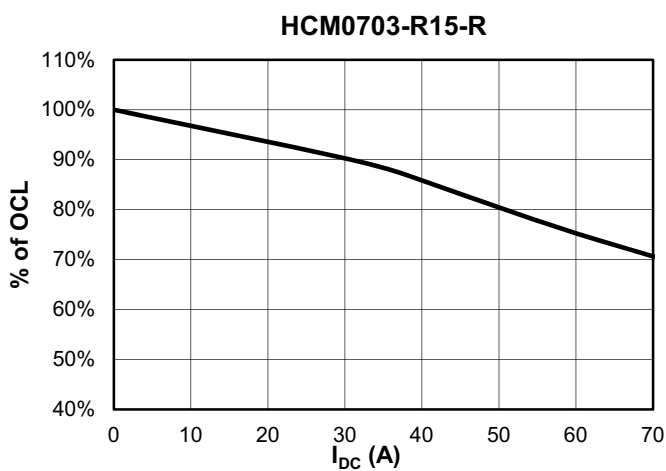
Temperature rise vs. total loss



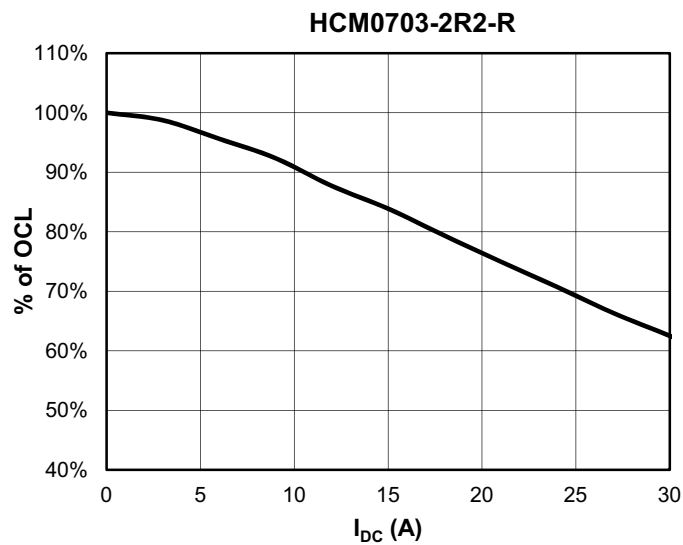
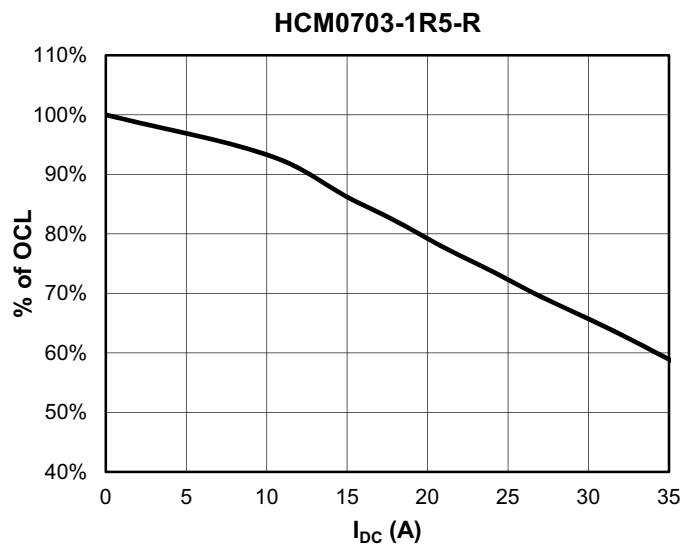
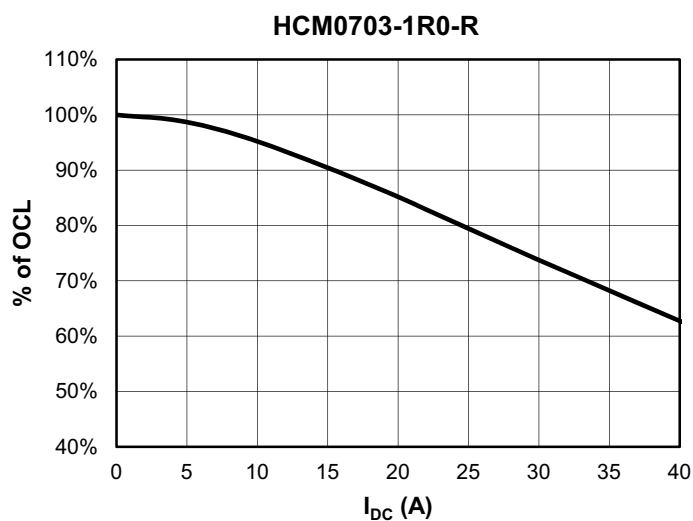
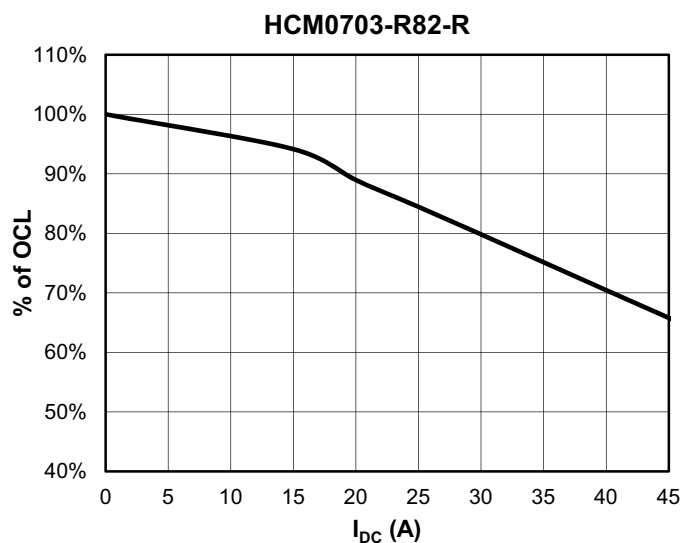
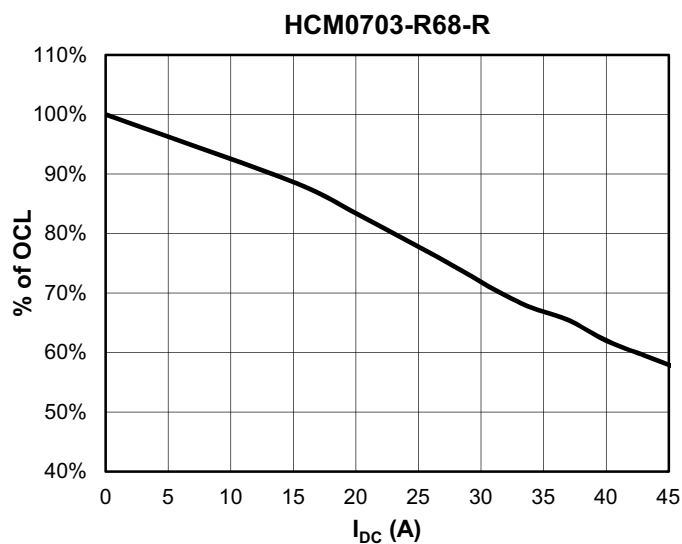
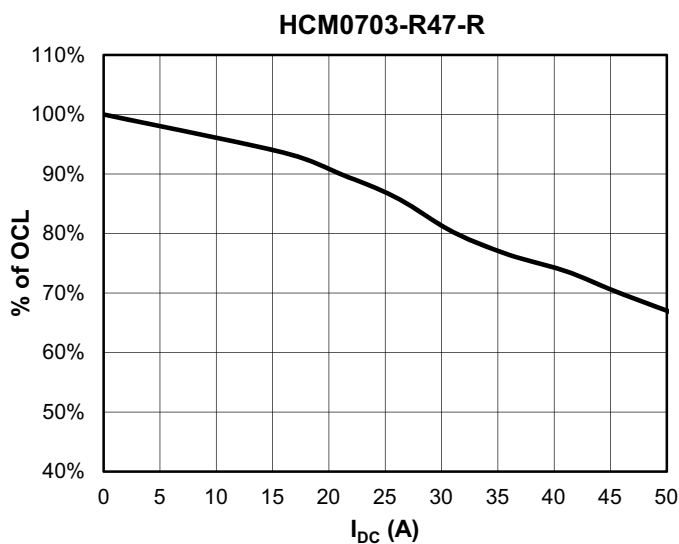
Core loss vs. B_{p-p}



Inductance characteristics

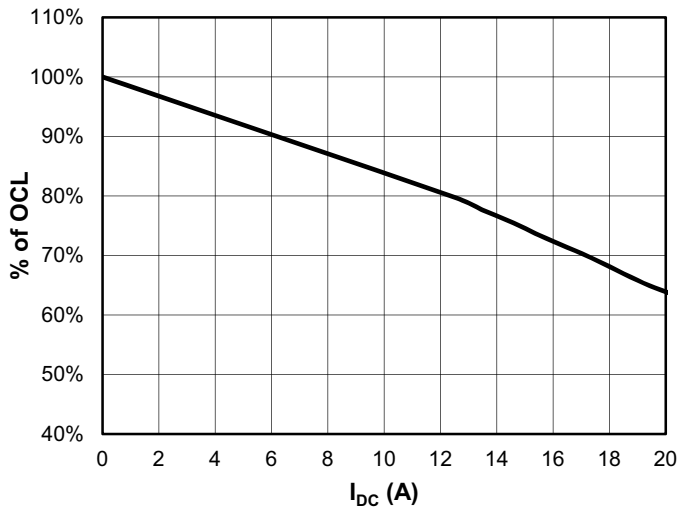


Inductance characteristics

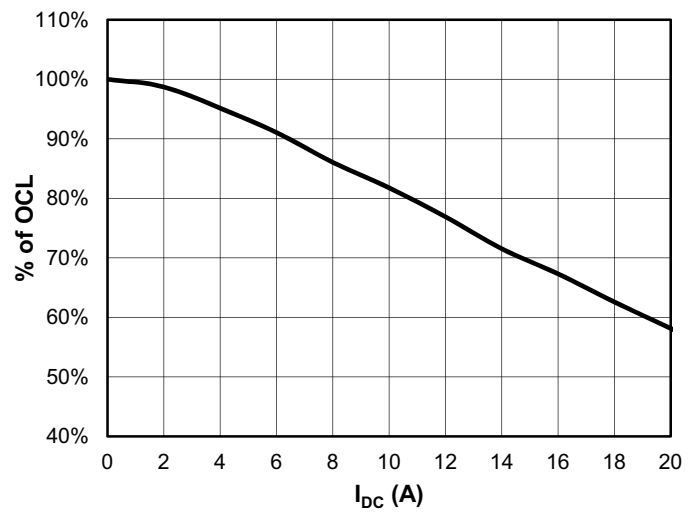


Inductance characteristics

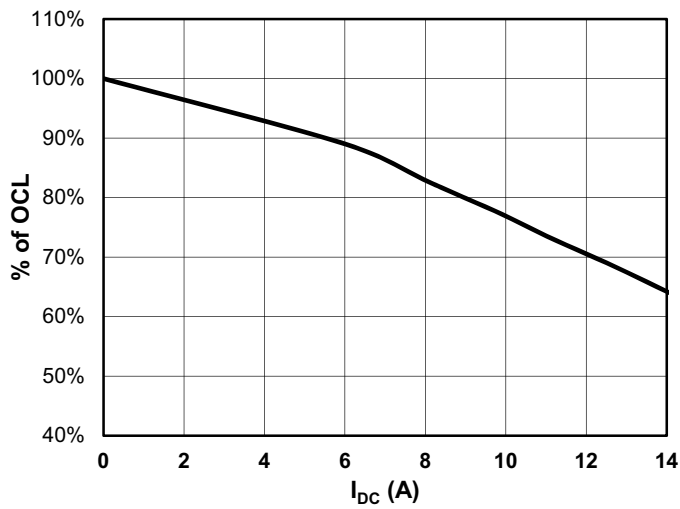
HCM0703-3R3-R



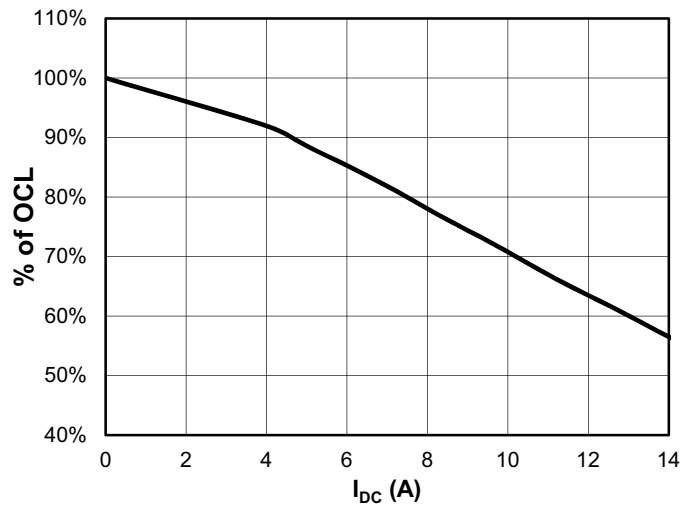
HCM0703-4R7-R



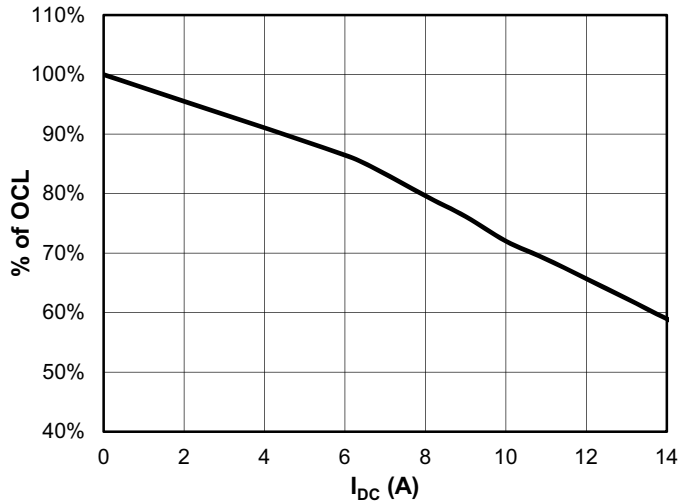
HCM0703-6R8-R



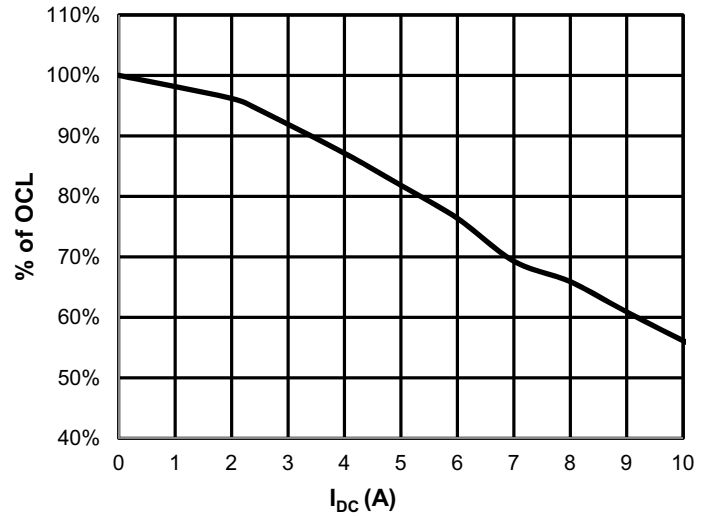
HCM0703-8R2-R



HCM0703-100-R

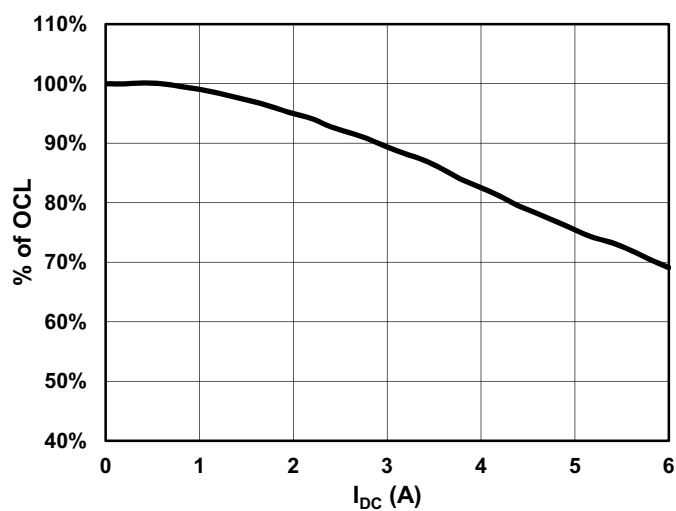


HCM0703-150-R

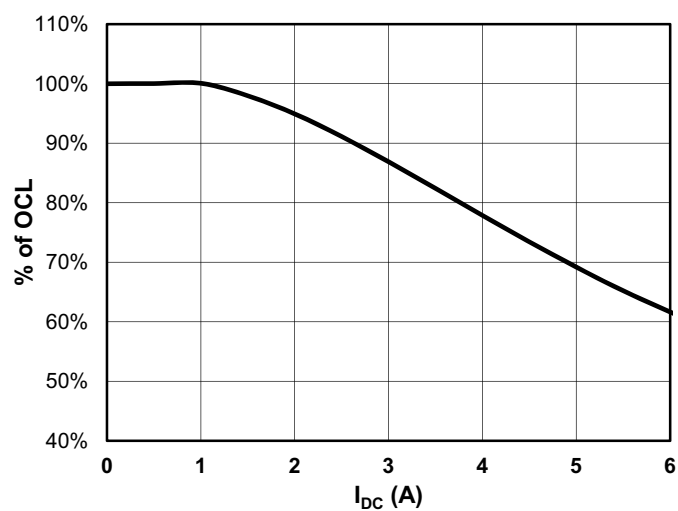


Inductance characteristics

HCM0703-220-R



HCM0703-330-R



Solder reflow profile

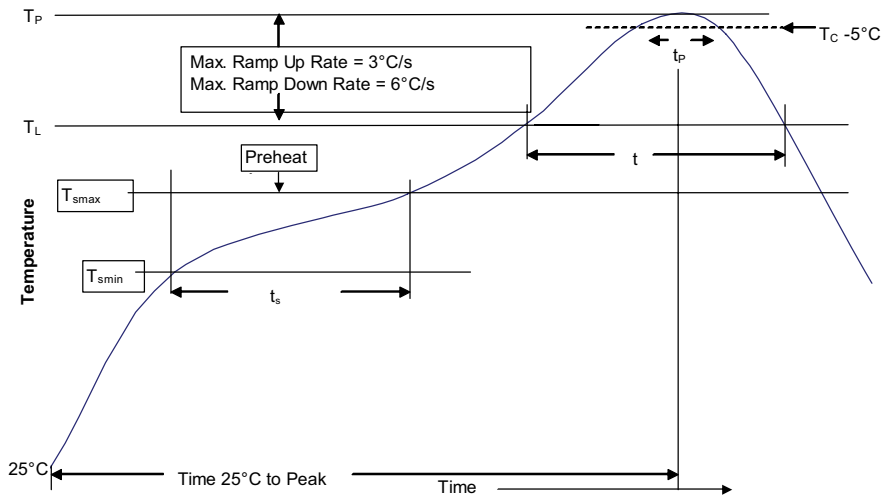


Table 1 - Standard SnPb Solder (T_C)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5 mm)	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2 - Lead (Pb) Free Solder (T_C)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 – 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245 °C

Reference JEDEC J-STD-020

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. (T_{smin})	100 °C	150 °C
• Temperature max. (T_{smax})	150 °C	200 °C
• Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds	60-120 seconds
Average ramp up rate T_{smax} to T_P	3 °C/ second Max.	3 °C/ second Max.
Liquidous temperature (T_L)	183°C	217°C
Time at liquidous (t_L)	60-150 seconds	60-150 seconds
Peak package body temperature (T_P)*	Table 1	Table 2
Time (t_p)** within 5 °C of the specified classification temperature (T_C)	20 seconds**	30 seconds**
Average ramp-down rate (T_P to T_{smax})	6 °C/ second Max.	6 °C/ second Max.
Time 25 °C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_P) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

Life Support Policy: Eaton does not authorize the use of any of its products for use in life support devices or systems without the express written approval of an officer of the Company. Life support systems are devices which support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.

Eaton reserves the right, without notice, to change design or construction of any products and to discontinue or limit distribution of any products. Eaton also reserves the right to change or update, without notice, any technical information contained in this bulletin.

Eaton
Electronics Division
1000 Eaton Boulevard
Cleveland, OH 44122
United States
www.eaton.com/electronics

© 2016 Eaton
All Rights Reserved
Printed in USA
Publication No. 4085 BU-MC16036
March 2016

EATON
Powering Business Worldwide

Eaton is a registered trademark.

All other trademarks are property of their respective owners.